

SPECIFICATIONS:

- Voltage rating: 30V AC/DC
- Current rating: 0.2A AC/DC
- Withstanding Voltage: 200V AC/minute
- Insulation resistance: 100MΩ Min.
- Temperature range: -25°C To +85°C
- Contact resistance: 30mΩ Max.

Standards

HSF

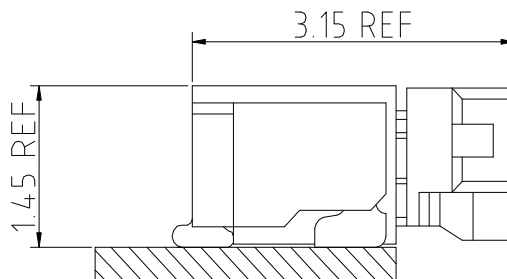


RoHS

Wire to Board

Assembly Layout

Right Angle Type



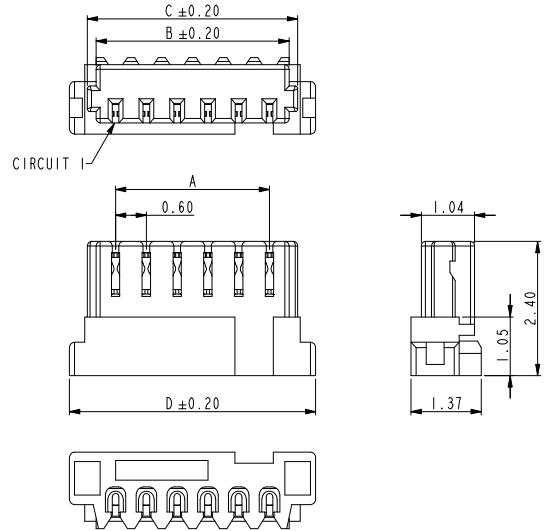
0.60mm Pitch IDC type connector

NOTES:

- MATERIAL:
INSULATOR(HALOGEN FREE): LCP, UL94V-0 (BLACK)
CONTACT: COPPER ALLOY
- CONTACT FINISH: AE--PRESSING BEFORE TIN-PLATED OVER NICKEL
GO--GOLD FLASH OVER NICKEL
- MATES WITH: TF0605 SERIES WAFER
- APPLICABLE WIRE: AWG #34
- INSULATION O.D.: $\phi 0.32\text{mm}$
- ORDERING CODE: AH0601-NP-X

NO. OF PINS | FINISH SEE NOTE 2
 02--2 PINS
 03--3 PINS

PIN	DIM.(mm)				PIN	DIM.(mm)			
	A	B	C	D		A	B	C	D
02		1.35	1.70	2.40	13	7.20	7.95	8.30	9.00
03	1.20	1.95	2.30	3.00	14	7.80	8.55	8.90	9.60
04	1.80	2.55	2.90	3.60	15	8.40	9.15	9.50	10.20
05	2.40	3.15	3.50	4.20	16	9.00	9.75	10.10	10.80
06	3.00	3.75	4.10	4.80	17	9.60	10.35	10.70	11.40
07	3.60	4.35	4.70	5.40	18	10.20	10.95	11.30	12.00
08	4.20	4.95	5.30	6.00	19	10.80	11.55	11.90	12.60
09	4.80	5.55	5.90	6.60	20	11.40	12.15	12.50	13.20
10	5.40	6.15	6.50	7.20	21	12.00	12.75	13.10	13.80
11	6.00	6.75	7.10	7.80	22	12.60	13.35	13.70	14.40
12	6.60	7.35	7.70	8.40					



0.60mm Pitch 90° Wafer-SMT type connector

NOTES:

- MATERIAL:
INSULATION(HALOGEN FREE): LCP, UL94V-0 (BLACK)
CONTACT: COPPER ALLOY, $t=0.12\text{mm}$
SOLDER TAB: COPPER ALLOY, $t=0.15\text{mm}$ / FINISH REFERENCE CONTACT
- CONTACT FINISH: (VOID)--MATTE-TIN PLATED OVER NICKEL
GO--GOLD FLASH OVER NICKEL
- ORDERING CODE: AW0601R-S-NP-X-NL-A

NO. OF PINS | TAPE REEL PACKING
 02--2 PINS | HALOGEN FREE
 03--3 PINS | FINISH SEE NOTE 2
 ↓
 22--22 PINS

Pins	A	B
4	1.80	4.20
5	2.40	4.80
6	3.00	5.40
8	4.20	6.60
10	5.40	7.80
12	6.60	9.00
16	9.00	11.40

